		Hits	Search Text	DBs
1	L1	28206 5	aperture or diaphram	EP©; JPO; DERW ENT; IBM_T DB
2	L2	52189 5	wafer or silicon	EPO; JPO; DERW ENT; IBM_T DB
3	L3	2988	(dope or doped or doping) with boron	EPO; JPO; DERW ENT; IBM_T DB
4	L4	23259 9	etch\$4	EPO; JPO; DERW ENT; IBM_T DB
5	L 5	13	1 and 2 and 3 and 4	EPO; JPO; DERW ENT; IBM_T DB
6	L6	19208 9	mask	EPO; JPO; DERW ENT; IBM_T DB
7	L7	22706	photomask or reticle	EPO; JPO; DERW ENT; IBM_T DB
8	L8	216	(6 or 7) and 2 and 3 and 4	EPO; JPO; DERW ENT; IBM_T DB
9	L10	68938	(mask or photomask or reticle).ti.	EPO; JPO; DERW ENT; IBM_T DB

	L#	Hits	Search Text	DBs
10	L11	49	8 and 10	EPO; JPO; DERW ENT; IBM_T DB
11	L12	1072	430/321.ccls.	USPA T; US-PG PUB
12	L13	3198	430/5.ccls.	USPA T; US-PG PUB
13	L14	717	216/2.ccls.	USPA T; US-PG PUB
14	L15	584	216/24.ccls.	USPA T; US-PG PUB
15	L17	72325	(wafer or silicon).ti,ab.	USPA T; US-PG PUB
16	L19	65439	(aperture or diaphram).ti,ab.	USPA T; US-PG PUB
17	L20	991	17 and 19	USPA T; US-PG PUB
18	L21	16477	(dope or doped or doping) with boron	USPA T; US-PG PUB
19	L22	68	20 and 21	USPA T; US-PG PUB
20	L23	32	12 and 19	USPA T; US-PG PUB
21	L24	27	20 and 13	USPA T; US-PG PUB

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	L#	Hits	Search Text	DBs
22	L25	529	((dope or doped or doping) with boron).ti,ab.	USPA T; US-PG PUB
23	L26	9	(12 or 13 or 14 or 15) and 25	USPA T; US-PG PUB
24	L27	2	15 and 20	USPA T; US-PG PUB
25	L28	35	19 and 14	USPA T; US-PG PUB

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